

## Version With Markings Showing Changes Made

### In the Claims:

Presented below are the amended claims in a marked-up version showing additions in underlined text, and deletions in brackets.

1. (Twice Amended) A method comprising:

placing an incomplete chip package into a mold formed by a first portion and a second portion, the incomplete chip package comprising a chip and a substrate electrically coupled using a flip chip process, the mold having an upper inner surface in which its entire length is coated with release film, and the chip having (i) a top surface facing the substrate, (ii) a bottom surface opposite the top surface, the bottom surface butting against the upper inner surface, and (iii) one or more side surfaces between the top and bottom surfaces;

injecting a liquid resin into a runner section of the mold, the runner formed [between] between <sup>the</sup> a first portion and the second portion, and the resin encapsulating a significant portion of the one or more side surfaces, and filling a first gap between the top surface and the adjacent substrate; and

curing the resin.

2. - 19. (Cancelled.)

1 20. (Twice Amended) A method comprising:

2 placing an incomplete flip chip package into a bottom inner cavity of a  
3 bottom mold portion[:], the incomplete flip chip package comprising  
4 a chip and a substrate, the chip having a top surface coupled by  
5 reflowed solder bumps to [a] an upper surface of the substrate, the  
6 chip further comprising a bottom surface opposite the top surface  
7 and one or more side surfaces between the top and bottom  
8 surfaces;

9 mating an upper mold portion with the lower mold portion, the upper mold  
10 portion having an upper inner cavity, including an upper inner  
11 surface in which its entire length is coated with a release film, and  
12 the bottom surface of the chip butts against the upper inner surface,  
13 the upper and bottom inner cavities forming a mold inner cavity  
14 enclosing the incomplete flip chip package, and forming a runner  
15 between the upper and lower mold portions;

16 injecting a predetermined amount of a liquid resin into the mold inner  
17 cavity through the runner, the liquid resin encapsulating  
18 substantially all or the one or more side surfaces and substantially  
19 all of the upper surface, the liquid resin further filling a gap between  
20 the top surface of the chip and an adjacent portion of the upper  
21 surface of the substrate, encapsulating the reflowed solder bumps;  
22 and

23 curing the liquid resin by maintaining the mold at an elevated temperature  
24 for a predetermined period of time, the elevated temperature being  
25 equal to or greater than the cure temperature of the filled liquid  
26 resin for the predetermined period of time.

1 21. - 26. (Cancelled.)

2 31. - 32. (Cancelled.)

1 33. - 36. (New)